

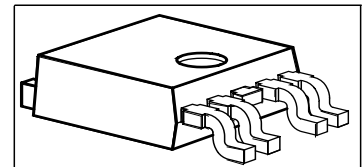
## Smart Power High-Side-Switch

### Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown with restart
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection with external resistor
- CMOS compatible input
- Loss of GND and loss of  $V_{bb}$  protection
- ESD - Protection
- Very low standby current

### Product Summary

Overvoltage protection	$V_{bb(AZ)}$	62	V
Operating voltage	$V_{bb(on)}$	6...52	V
On-state resistance	$R_{ON}$	200	m $\Omega$
Nominal load current	$I_{L(ISO)}$	1.8	A



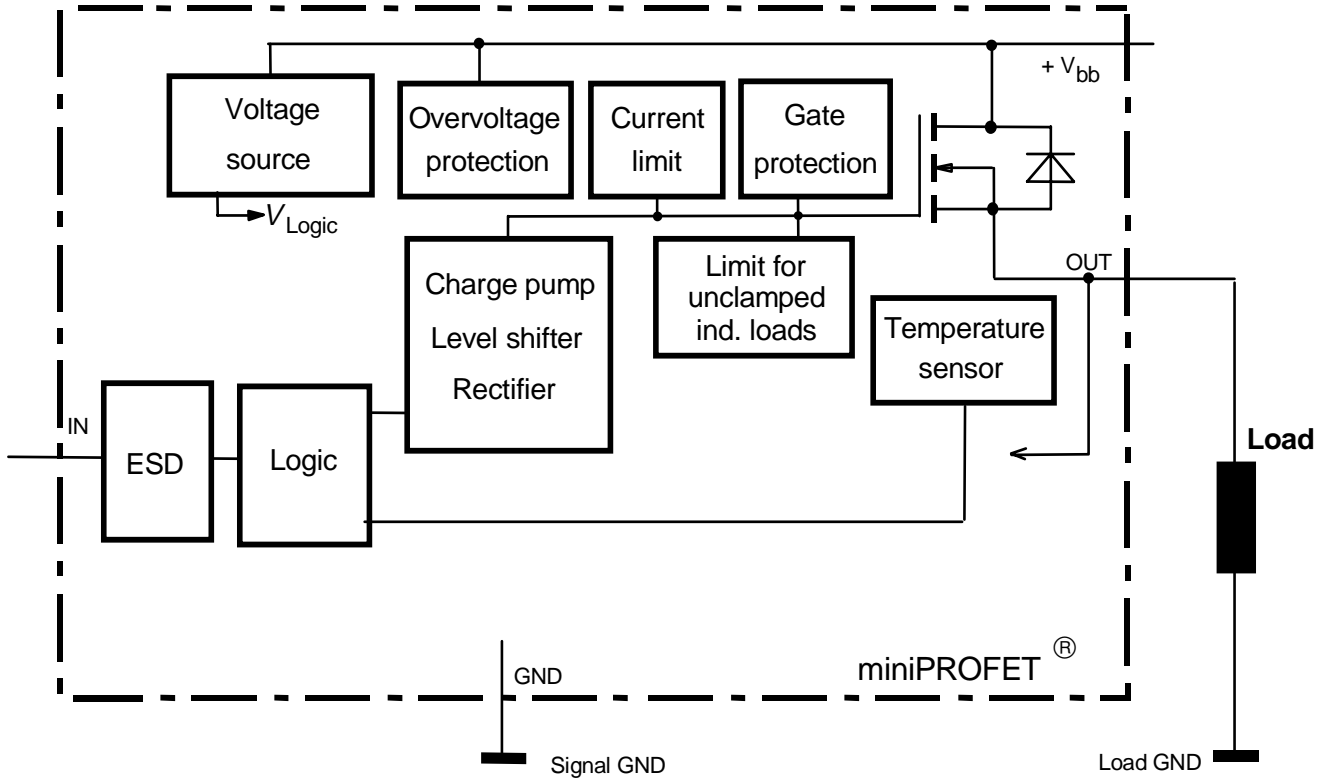
### Application

- All types of resistive, inductive and capacitive loads
- $\mu$ C compatible power switch for 12 V, 24 V and 42 V DC applications
- Replaces electromechanical relays and discrete circuits

### General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input, monolithically integrated in Smart SIPMOS<sup>®</sup> technology. Fully protected by embedded protection functions.

### Block Diagram



Pin	Symbol	Function
1	GND	Logic ground
2	IN	Input, activates the power switch in case of logic high signal
3	Vbb	Positive power supply voltage
4	NC	not connected
5	OUT	Output to the load
TAB	Vbb	Positive power supply voltage

**Maximum Ratings at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Value	Unit
Supply voltage	$V_{bb}$	52	V
Supply voltage for full short circuit protection	$V_{bb(SC)}$	50	
Continuous input voltage	$V_{IN}$	-10 ... +16	
Load current (Short - circuit current, see page 5)	$I_L$	self limited	A
Current through input pin (DC)	$I_{IN}$	$\pm 5$	mA
Operating temperature	$T_j$	-40 ... +150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 ... +150	
Power dissipation <sup>1)</sup>	$P_{tot}$	41.6	W
Inductive load switch-off energy dissipation <sup>1)2)</sup> single pulse, (see page 8) $T_j = 150^\circ\text{C}$ , $I_L = 1\text{ A}$	$E_{AS}$	150	mJ
Load dump protection <sup>2)</sup> $V_{LoadDump}^{3)} = V_A + V_S$ $R_I = 2\Omega$ , $t_d = 400\text{ms}$ , $V_{IN} = \text{low or high}$ , $V_A = 13,5\text{V}$ $R_L = 13.5\ \Omega$ $R_L = 27\ \Omega$	$V_{Loaddump}$	73.5 88.5	V
<b>Electrostatic discharge voltage (Human Body Model)</b> according to ANSI EOS/ESD - S5.1 - 1993 ESD STM5.1 - 1998 Input pin all other pins	$V_{ESD}$	$\pm 1$ $\pm 5$	kV

**Thermal Characteristics**

junction - case:	$R_{thJC}$	-	-	3	K/W
Thermal resistance @ min. footprint	$R_{th(JA)}$	-	80	-	K/W
Thermal resistance @ 6 cm <sup>2</sup> cooling area <sup>1)</sup>	$R_{th(JA)}$	-	45	60	

<sup>1)</sup>Device on 50mm\*50mm\*1.5mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

<sup>2)</sup>not tested, specified by design

<sup>3)</sup> $V_{Loaddump}$  is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839 .

Supply voltages higher than  $V_{bb(AZ)}$  require an external current limit for the GND pin, e.g. with a 150Ω resistor in GND connection. A resistor for the protection of the input is integrated.

**Electrical Characteristics**

Parameter and Conditions	Symbol	Values			Unit
		min.	typ.	max.	
at $T_j = -40...150^\circ\text{C}$ , $V_{bb} = 12..42\text{V}$ , unless otherwise specified					

**Load Switching Capabilities and Characteristics**

On-state resistance $T_j = 25^\circ\text{C}$ , $I_L = 1\text{ A}$ , $V_{bb} = 9...52\text{ V}$ $T_j = 150^\circ\text{C}$	$R_{ON}$	-	150	200	m $\Omega$
Nominal load current; Device on PCB <sup>1)</sup> $T_C = 85^\circ\text{C}$ , $V_{ON} = 0.5\text{ V}$	$I_{L(ISO)}$	1.8	2.2	-	A
Turn-on time to 90% $V_{OUT}$ $R_L = 47\ \Omega$	$t_{on}$	-	80	180	$\mu\text{s}$
Turn-off time to 10% $V_{OUT}$ $R_L = 47\ \Omega$	$t_{off}$	-	80	200	
Slew rate on 10 to 30% $V_{OUT}$ , $R_L = 47\ \Omega$ , $V_{bb} = 13.5\text{ V}$	$dV/dt_{on}$	-	0.7	2	V/ $\mu\text{s}$
Slew rate off 70 to 40% $V_{OUT}$ , $R_L = 47\ \Omega$ , $V_{bb} = 13.5\text{ V}$	$-dV/dt_{off}$	-	0.9	2	

**Operating Parameters**

Operating voltage	$V_{bb(on)}$	6	-	52	V
Undervoltage shutdown of charge pump $T_j = -40...+85^\circ\text{C}$ $T_j = 150^\circ\text{C}$	$V_{bb(under)}$	-	-	4	
Undervoltage restart of charge pump	$V_{bb(u\ cp)}$	-	4	5.5	
Standby current $T_j = -40...+85^\circ\text{C}$ , $V_{IN} = \text{low}$ $T_j = +150^\circ\text{C}^2)$ , $V_{IN} = \text{low}$	$I_{bb(off)}$	-	-	15	$\mu\text{A}$
Leakage output current (included in $I_{bb(off)}$ ) $V_{IN} = \text{low}$	$I_{L(off)}$	-	-	5	
Operating current $V_{IN} = \text{high}$	$I_{GND}$	-	0.8	2	mA

<sup>1</sup>Device on 50mm\*50mm\*1.5mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

<sup>2</sup>higher current due temperature sensor

**Electrical Characteristics**

Parameter and Conditions	Symbol	Values			Unit
		min.	typ.	max.	
at $T_j = -40...150^\circ\text{C}$ , $V_{bb} = 12..42\text{V}$ , unless otherwise specified					
<b>Protection Functions</b>					
Initial peak short circuit current limit (pin 3 to 5) $T_j = -40^\circ\text{C}$ , $V_{bb} = 20\text{V}$ , $t_m = 150\ \mu\text{s}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ $T_j = -40...+150^\circ\text{C}$ , $V_{bb} > 40\text{V}$ , ( see page 11 )	$I_{L(SCp)}$	- - 4 -	- 6.5 - 5 <sup>1)</sup>	9 - - -	A
Repetitive short circuit current limit $T_j = T_{jt}$ (see timing diagrams) $V_{bb} < 40\text{V}$ $V_{bb} > 40\text{V}$	$I_{L(SCr)}$	- -	6 4.5	- -	
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$ , $I_{bb} = 4\text{mA}$	$V_{ON(CL)}$	59	63	-	V
Overvoltage protection <sup>2)</sup> $I_{bb} = 4\text{mA}$	$V_{bb(AZ)}$	62	-	-	
Thermal overload trip temperature	$T_{jt}$	150	-	-	$^\circ\text{C}$
Thermal hysteresis	$\Delta T_{jt}$	-	10	-	K
<b>Reverse Battery</b>					
Reverse battery <sup>3)</sup>	$-V_{bb}$	-	-	52	V
Drain-source diode voltage ( $V_{OUT} > V_{bb}$ ) $T_j = 150^\circ\text{C}$	$-V_{ON}$	-	600	-	mV

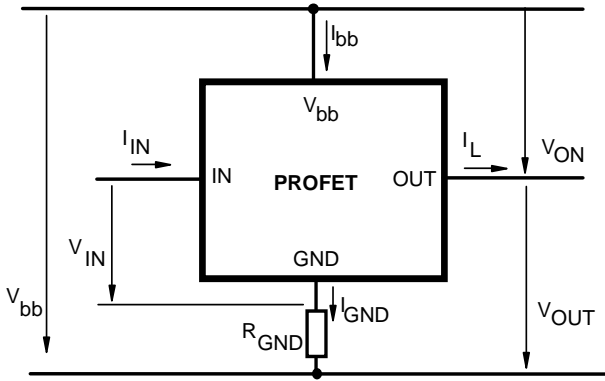
<sup>1</sup>not tested, specified by design

<sup>2</sup> see also  $V_{ON(CL)}$  in circuit diagram on page 7

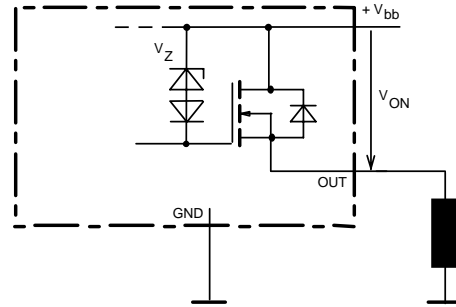
<sup>3</sup>Requires a 150  $\Omega$  resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Power dissipation is higher compared to normal operating conditions due to the voltage drop across the drain-source diode. The temperature protection is not active during reverse current operation! Input current has to be limited (see max. ratings page 3).

Parameter and Conditions at $T_j = -40...150^{\circ}\text{C}$ , $V_{bb} = 12..42\text{V}$ , unless otherwise specified	Symbol	Values			Unit
		min.	typ.	max.	
<b>Input</b>					
Input turn-on threshold voltage	$V_{IN(T+)}$	-	-	2.2	V
Input turn-off threshold voltage	$V_{IN(T-)}$	0.8	-	-	
Input threshold hysteresis	$\Delta V_{IN(T)}$	-	0.4	-	
Off state input current $V_{IN} = 0.7\text{ V}$	$I_{IN(off)}$	1	-	25	$\mu\text{A}$
On state input current $V_{IN} = 5\text{ V}$	$I_{IN(on)}$	3	-	25	
Input resistance (see page 7)	$R_I$	2	3.5	5	$\text{k}\Omega$

**Terms**

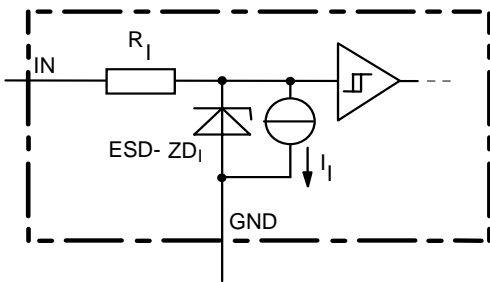


**Inductive and overvoltage output clamp**



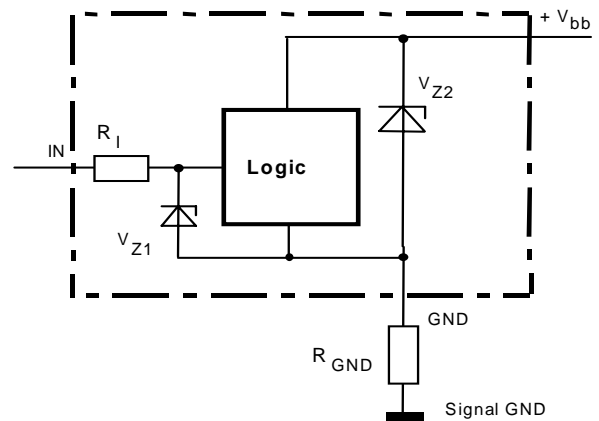
$V_{ON}$  clamped to 59V min.

**Input circuit (ESD protection)**



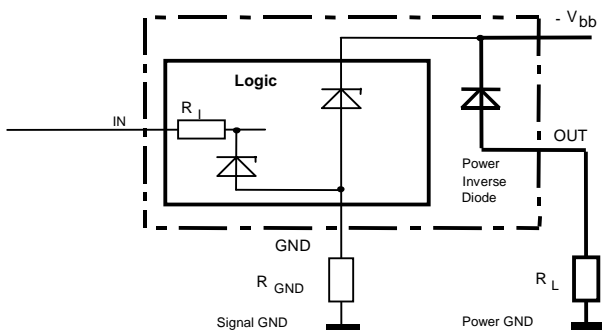
The use of ESD zener diodes as voltage clamp at DC conditions is not recommended

**Overvoltage protection of logic part**



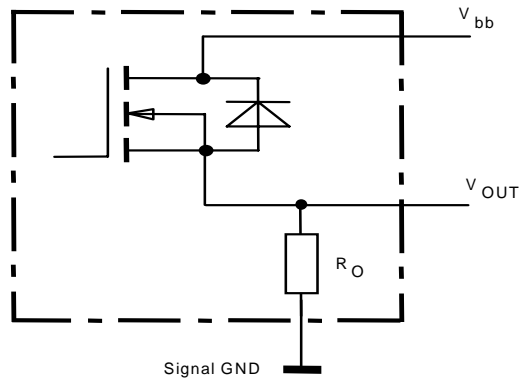
$V_{Z1}=6.1V$  typ.,  $V_{Z2}=V_{bb}(AZ)=62V$  min.,  
 $R_I=3.5\text{ k}\Omega$  typ.,  $R_{GND}=150\Omega$

**Reverse battery protection**



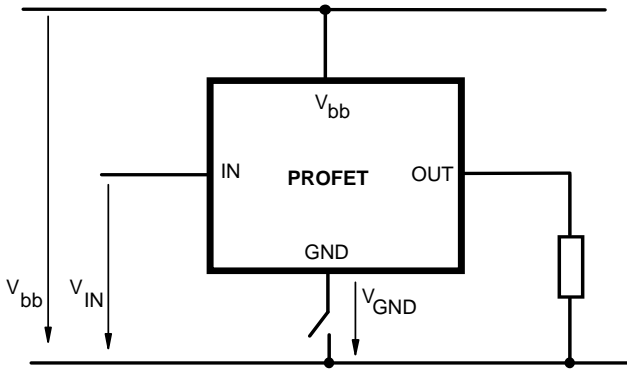
$R_{GND}=150\Omega$ ,  $R_I=3.5\text{ k}\Omega$  typ.,  
 Temperature protection is not active during inverse current

**Internal output pull down**

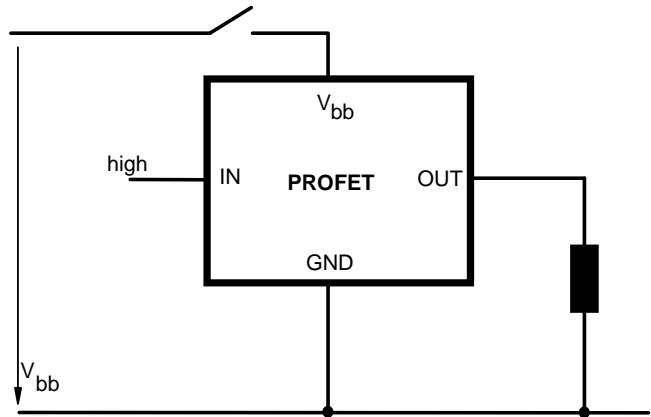


$R_O = 200\text{ k}\Omega$  typ.

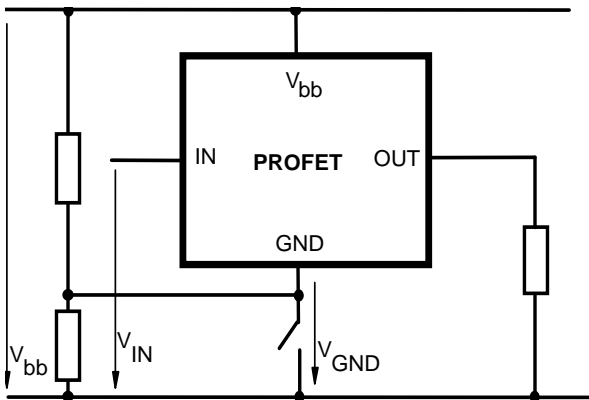
**GND disconnect**



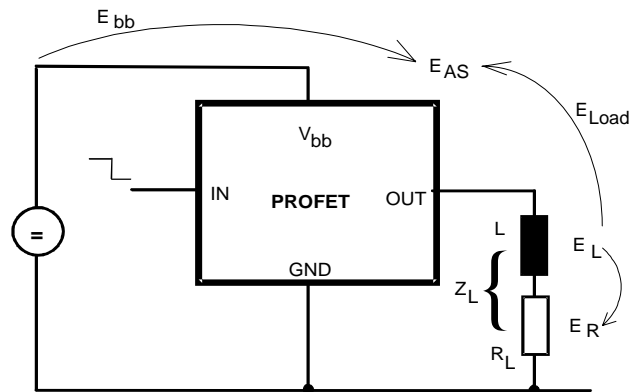
**V<sub>bb</sub> disconnect with charged inductive load**



**GND disconnect with GND pull up**



**Inductive Load switch-off energy dissipation**



Energy stored in load inductance:  $E_L = \frac{1}{2} * L * I_L^2$

While demagnetizing load inductance, the energy dissipated in PROFET is  $E_{AS} = E_{bb} + E_L - E_R = \int V_{ON(CL)} * i_L(t) dt$ , with an approximate solution for  $R_L > 0\Omega$ :

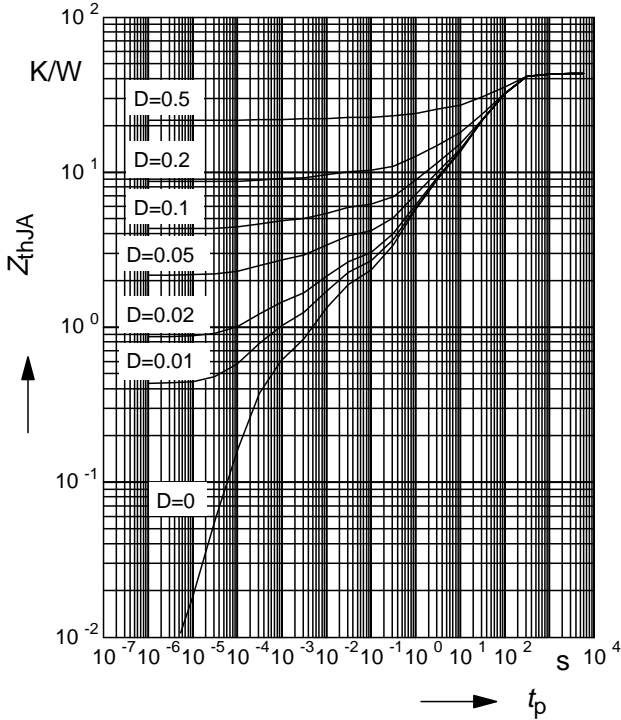
$$E_{AS} = \frac{I_L * L}{2 * R_L} * (V_{bb} + |V_{OUT(CL)}|) * \ln\left(1 + \frac{I_L * R_L}{|V_{OUT(CL)}|}\right)$$



**Typ. transient thermal impedance**

$Z_{thJA}=f(t_p)$  @ 6cm<sup>2</sup> heatsink area

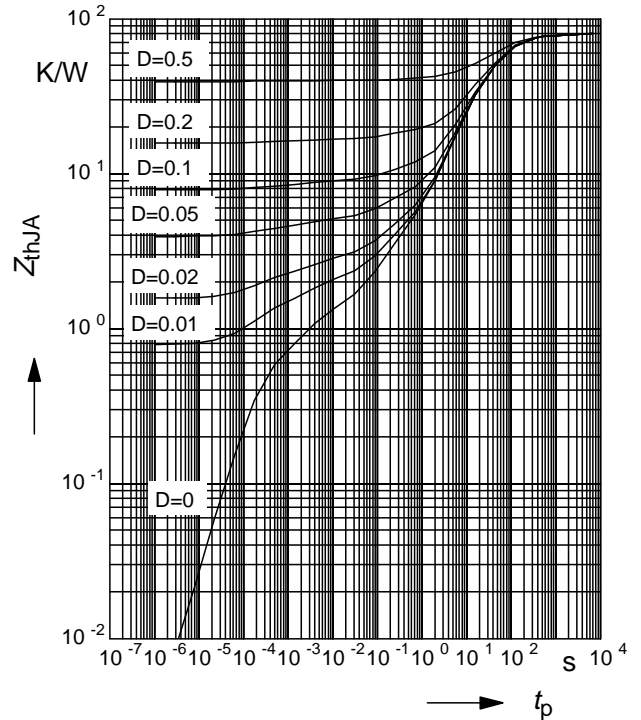
Parameter:  $D=t_p/T$



**Typ. transient thermal impedance**

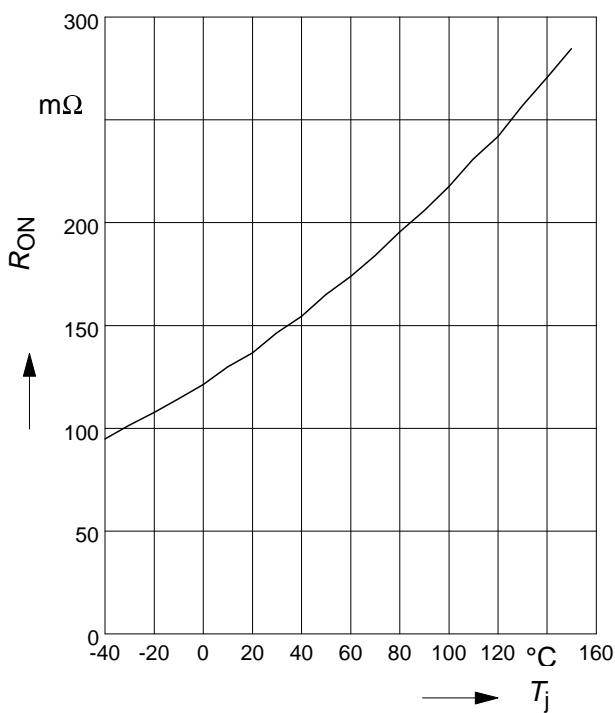
$Z_{thJA}=f(t_p)$  @ min. footprint

Parameter:  $D=t_p/T$



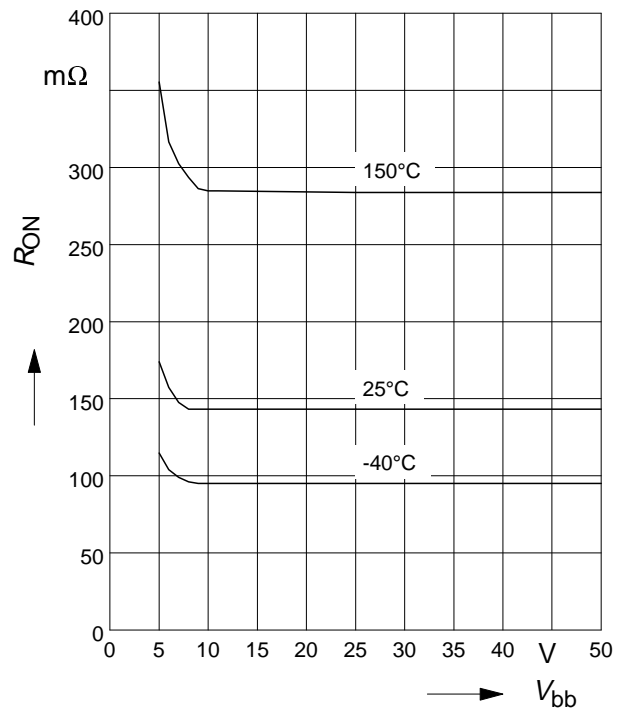
**Typ. on-state resistance**

$R_{ON} = f(T_j)$ ;  $V_{bb} = 13,5V$ ;  $V_{in} = \text{high}$



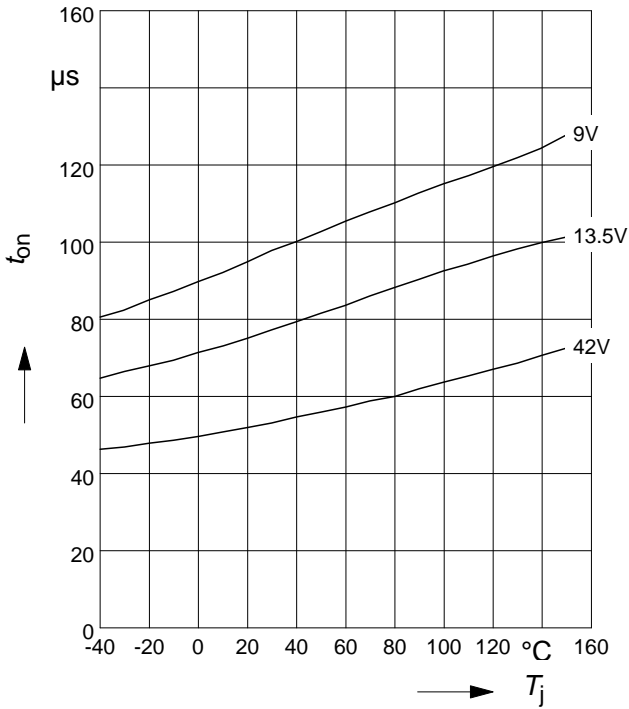
**Typ. on-state resistance**

$R_{ON} = f(V_{bb})$ ;  $I_L = 1 A$ ;  $V_{in} = \text{high}$



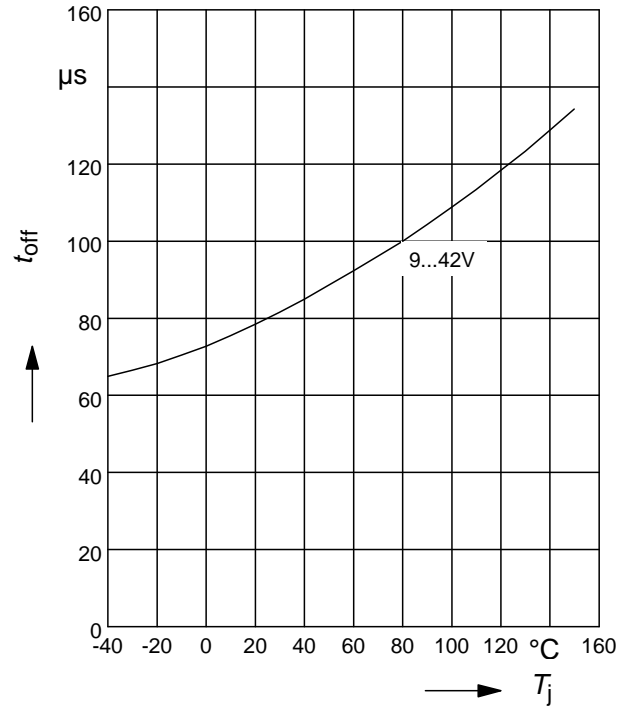
**Typ. turn on time**

$t_{on} = f(T_j); R_L = 47\Omega$



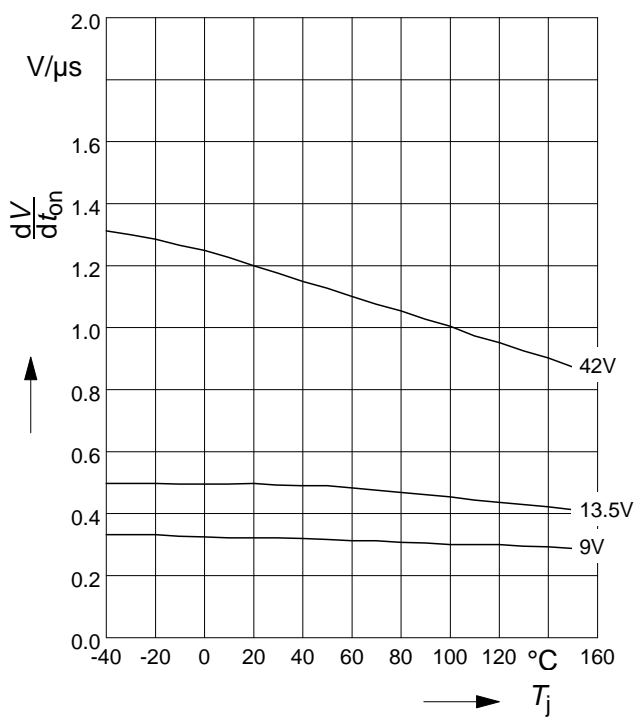
**Typ. turn off time**

$t_{off} = f(T_j); R_L = 47\Omega$



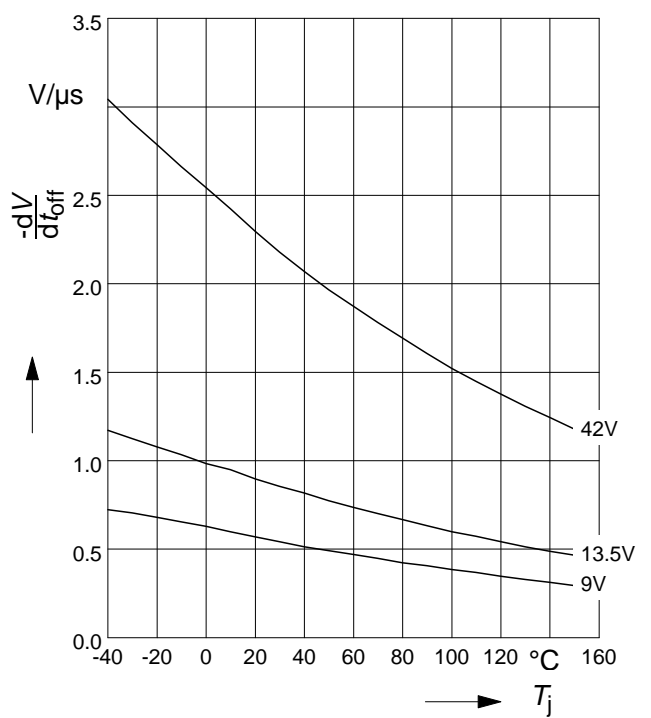
**Typ. slew rate on**

$dV/dt_{on} = f(T_j); R_L = 47\Omega$



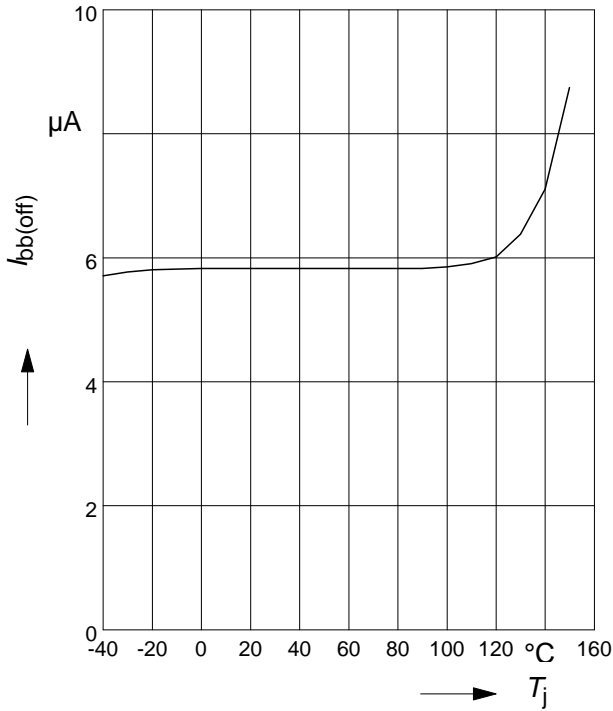
**Typ. slew rate off**

$-dV/dt_{off} = f(T_j); R_L = 47\Omega$



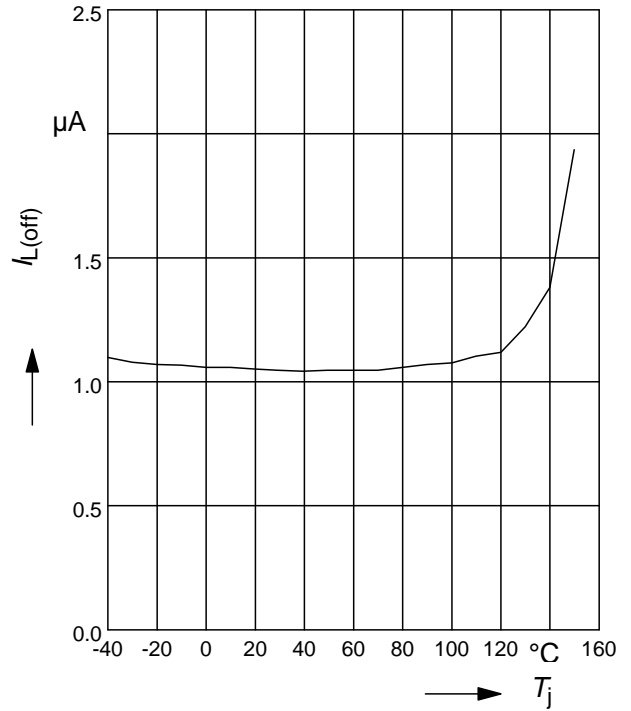
**Typ. standby current**

$I_{bb(off)} = f(T_j)$ ;  $V_{bb} = 42V$ ;  $V_{IN} = low$



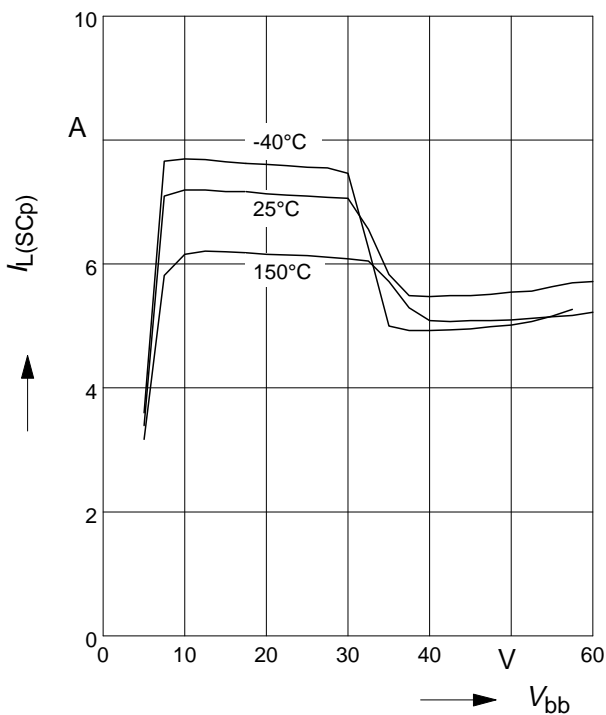
**Typ. leakage current**

$I_{L(off)} = f(T_j)$ ;  $V_{bb} = 42V$ ;  $V_{IN} = low$



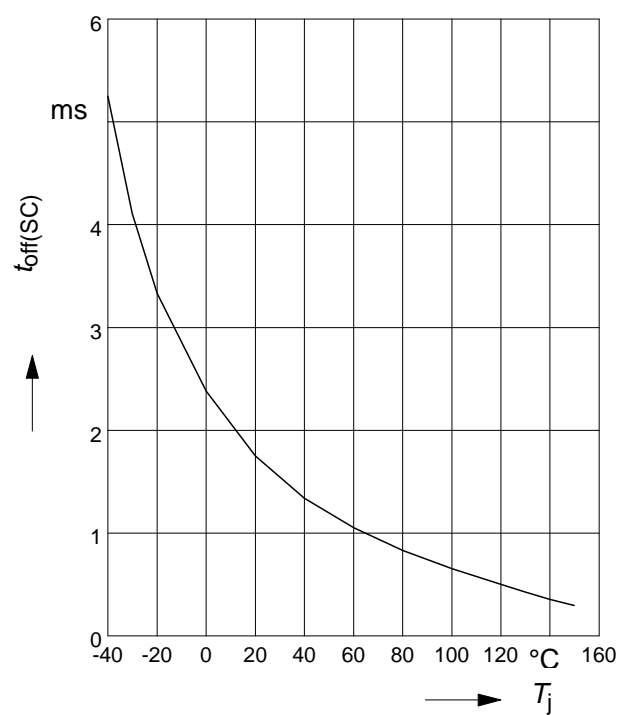
**Typ. initial peak short circuit current limit**

$I_{L(SCp)} = f(V_{bb})$



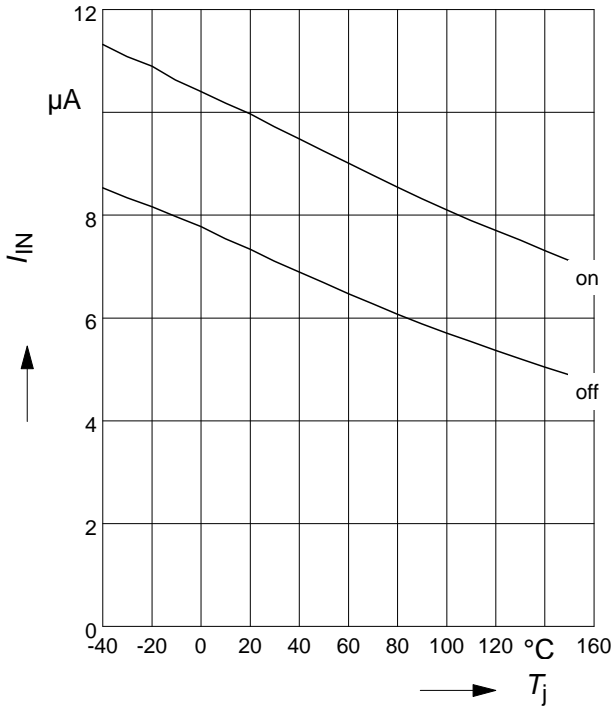
**Typ. initial short circuit shutdown time**

$t_{off(SC)} = f(T_{j,start})$ ;  $V_{bb} = 20V$



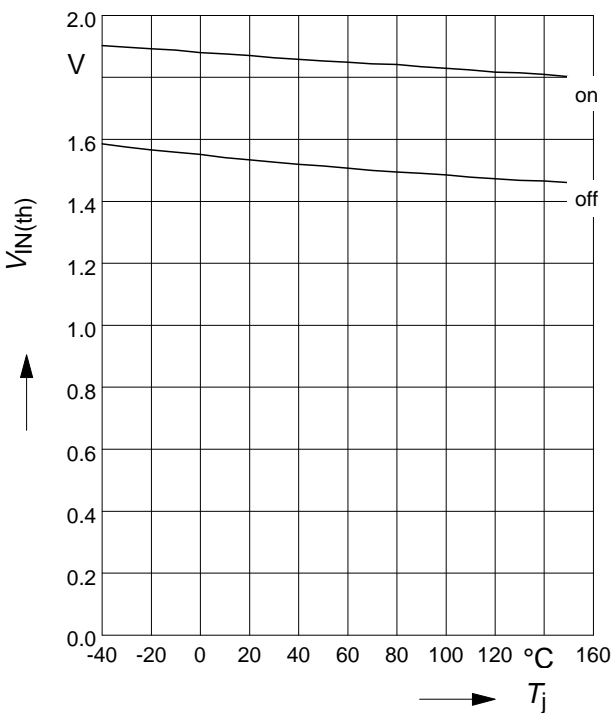
**Typ. input current**

$I_{IN(on/off)} = f(T_j)$ ;  $V_{bb} = 13,5V$ ;  $V_{IN} = \text{low/high}$   
 $V_{INlow} \leq 0,7V$ ;  $V_{INhigh} = 5V$



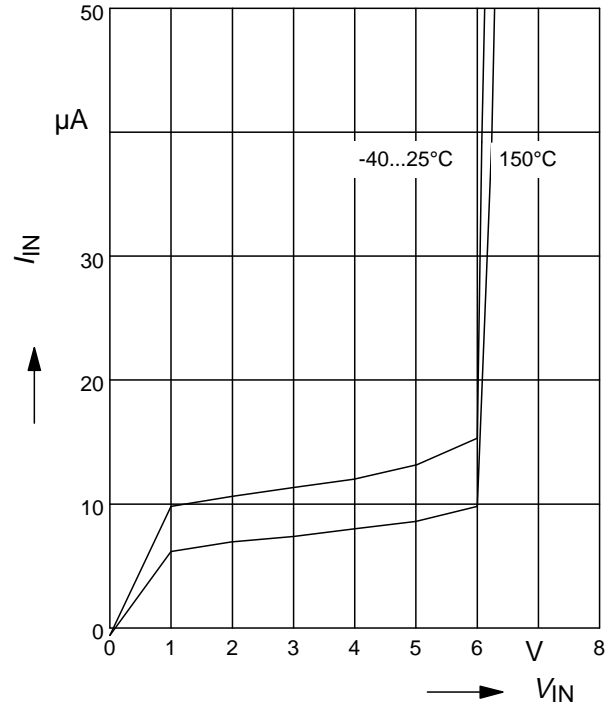
**Typ. input threshold voltage**

$V_{IN(th)} = f(T_j)$ ;  $V_{bb} = 13,5V$



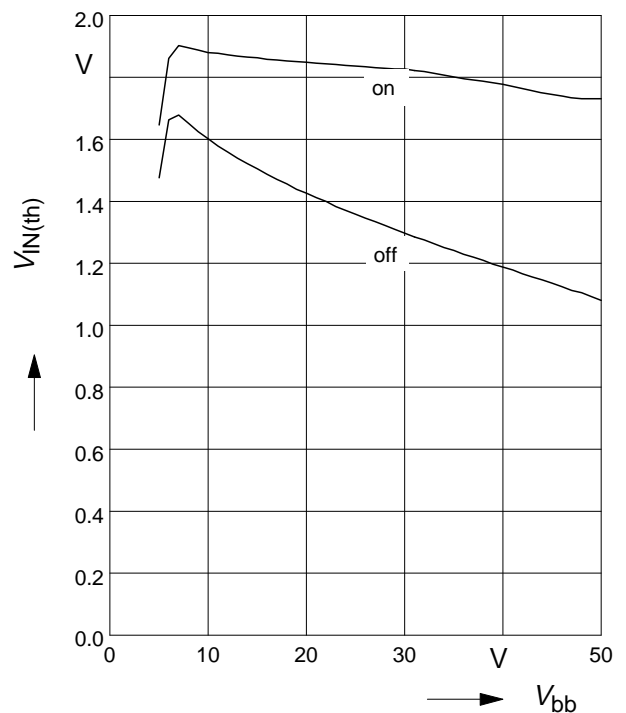
**Typ. input current**

$I_{IN} = f(V_{IN})$ ;  $V_{bb} = 13.5V$



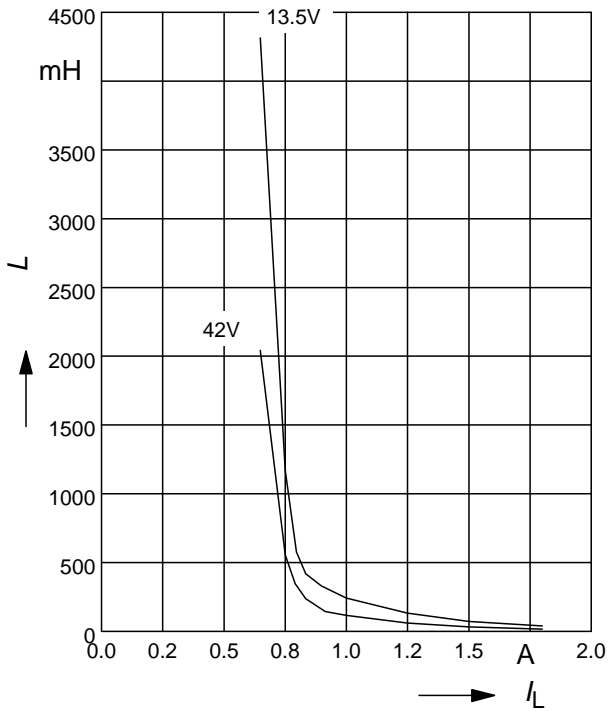
**Typ. input threshold voltage**

$V_{IN(th)} = f(V_{bb})$ ;  $T_j = 25^{\circ}C$



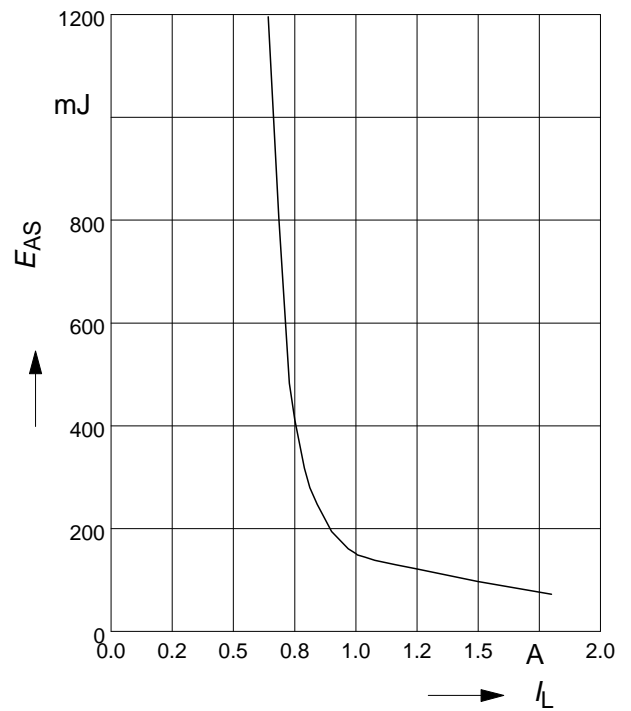
**Maximum allowable load inductance for a single switch off**

$L = f(I_L); T_{jstart}=150^{\circ}\text{C}, R_L=0\Omega$



**Maximum allowable inductive switch-off energy, single pulse**

$E_{AS} = f(I_L); T_{jstart} = 150^{\circ}\text{C}, V_{bb} = 13,5\text{V}$



## Timing diagrams

Figure 1a: V<sub>bb</sub> turn on:

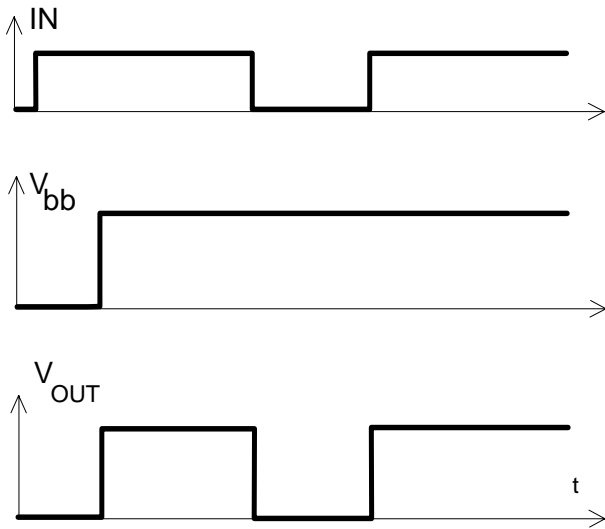


Figure 2b: Switching a lamp,

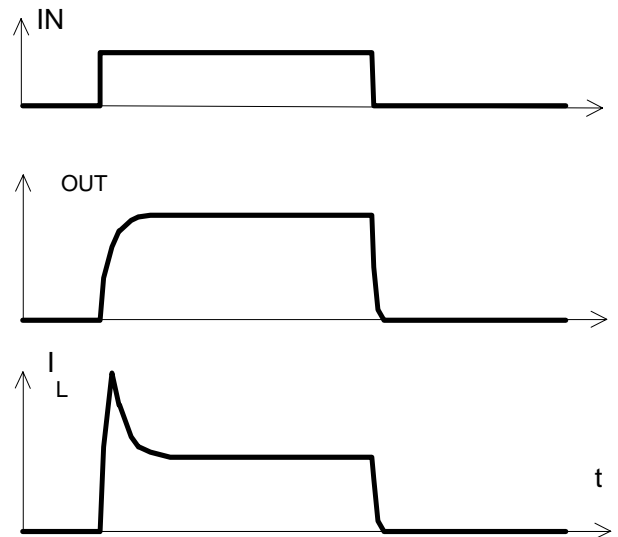


Figure 2a: Switching a resistive load, turn-on/off time and slew rate definition

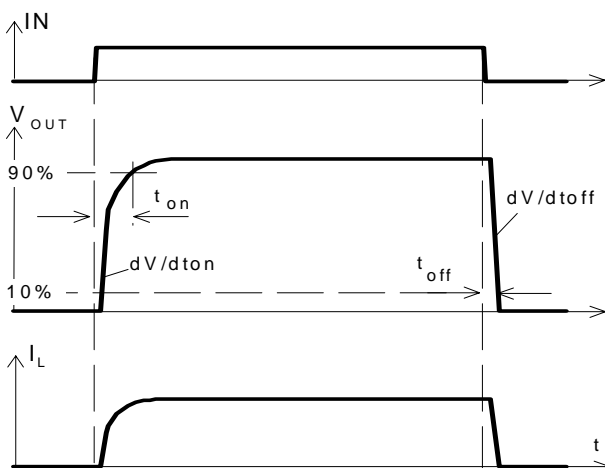
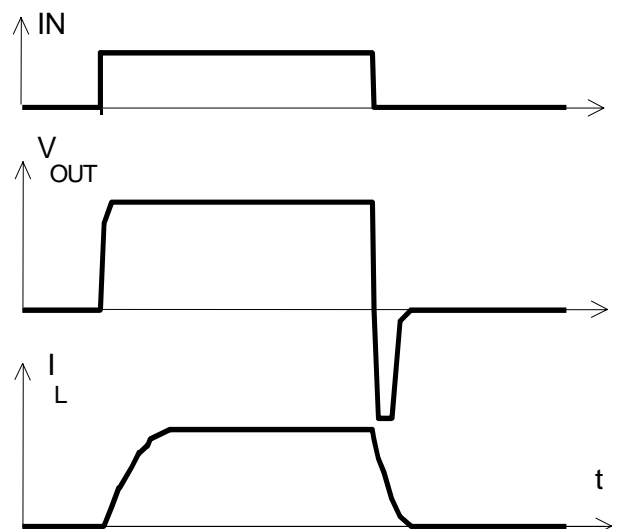
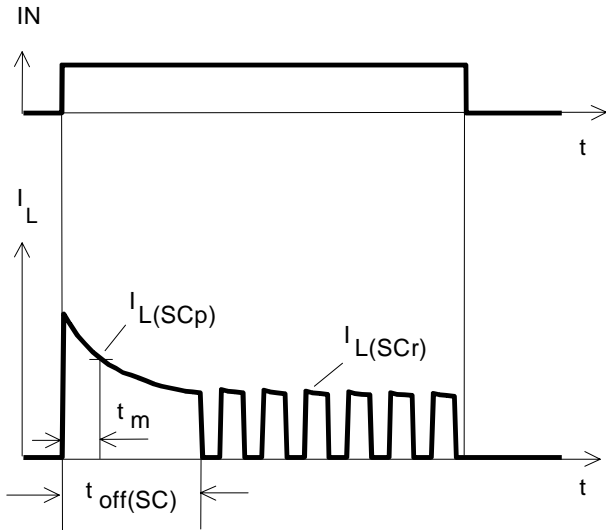


Figure 2c: Switching an inductive load

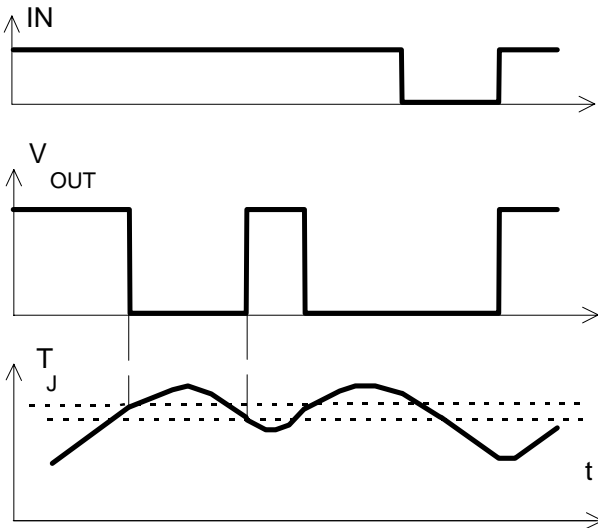


**Figure 3a:** Turn on into short circuit, shut down by overtemperature, restart by cooling

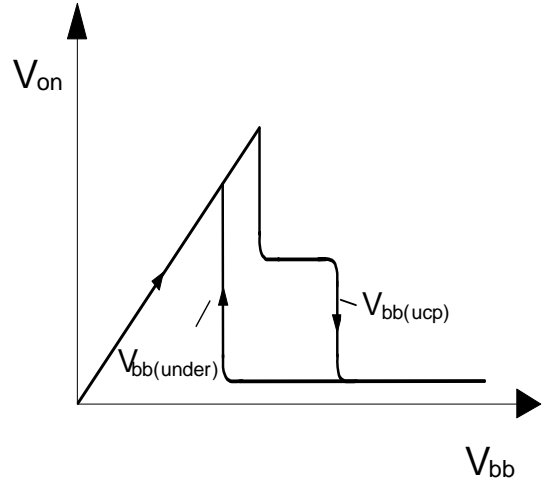


Heating up of the chip may require several milliseconds, depending on external conditions.

**Figure 4:** Overtemperature: Reset if  $T_j < T_{jt}$



**Figure 5:** Undervoltage restart of charge pump

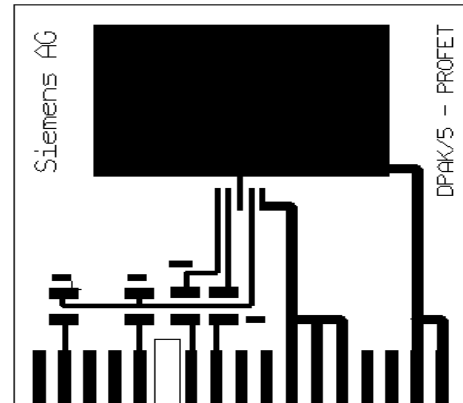
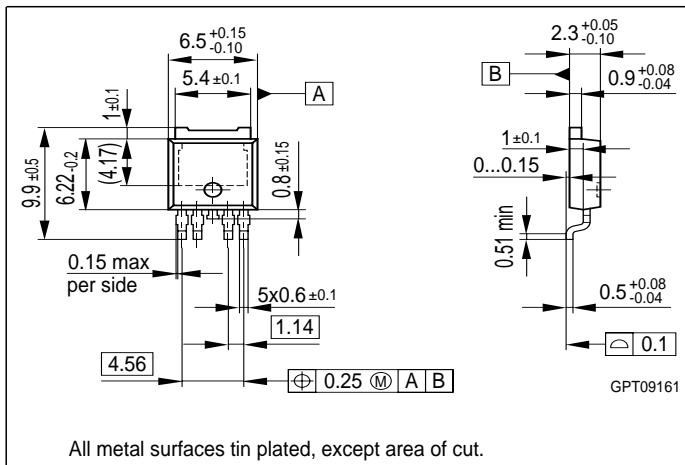


## Package and ordering code

all dimensions in mm

Ordering code:

Q67060-S7406
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Printed circuit board (FR4, 1.5mm thick, one layer 70µm, 6cm<sup>2</sup> active heatsink area) as a reference for max. power dissipation  $P_{tot}$  nominal load current  $I_{L(nom)}$  and thermal resistance  $R_{thja}$

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